

CLIPPEDIMAGE= JP410270817A

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TITLE: CIRCUIT BOARD, SUSPENSION BOARD WITH CIRCUIT, AND THEIR MANUFACTURE

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ABSTRACT:

PROBLEM TO BE SOLVED: To provide a circuit board which has an insulating layer made of a polyimide resin having a low hygroscopic property and formed on a metallic foil substrate and such high dimensional stability that the board does not warp even when the moisture in the environmental atmosphere changes and a suspension board with circuit using the circuit board.

SOLUTION: In a circuit board having an insulating layer 3 made of a polyimide resin and formed on a metallic foil substrate 2, the insulating layer 3 is formed by using a polyimide resin which is obtained through the reaction

between an aromatic diamine composed of  
1,3-bis(4-aminophenoxy) benzene and  
2,2'-bis(trifluoromethyl)-4,4'-diaminobiphenyl and an  
aromatic tetracarboxylic  
acid dianhydride composed of 3,4,3',4'-biphenyl  
tetracarboxylic acid  
dianhydride and 2,2-bis(3,4-dicarboxyphenyl)  
hexafluoropropane dianhydride. A  
suspension board 1 with circuit is formed by patterning a  
desired circuit  
composed of a conductor layer on such a circuit board.

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